

JICHENGJS (DONGGUAN) CO,LTD

TECHINHERIT

Conductive PC

Product Features and Applications

Electronic device housings, semiconductor trays, anti-static (ESD) packaging, battery components, medical device housings, Industrial electronic components

性能 Property	测试标准 Standard Test	测试条件 Test Condition	单位 Unit	数值 Value
机械性能 Mechanical Properties				
拉伸强度 Tensile Strength@Yield	GB/T 1040	50mm/min	Mpa	58.00
断裂伸长率 Elongation at Break	GB/T 1040	50mm/min	%	8.00
弯曲强度 Flexural Yield Strength	GB/T9341	2mm/min	Mpa	95.00
弯曲模量 Flexural Modulus	GB/T9341	2mm/min	Mpa	3600.00
缺口冲击强度 Izod Impact, Notched	ASTM D256	3.2mm	KJ/M²	28.00
	ASTM D256	3.2mm	KJ/M²	18.00
Physical Properties				
熔融指数 Melt Flow	GB/T 3682	300℃,1.2kg	g/10min	9.00
流动方向收缩率 Linear Mold Shrinkage	ASTM D955	--	%	0.4
垂直方向收缩率 Linear Mold Shrinkage	ASTM D955	--	%	0.60
密度 Density	GB/T 1033	23℃	g/cm3	1.24
热性能 Thermal Properties				
热变形温度 heat deflection temperature	GB/T 1634	1.8 MPa	℃	125
阻燃性能 flammability	UL94	1.5 mm	Class	HB
Electrical Properties				
体积电阻 Volume Resistivity	ASTM D 257		--	
Processing				
干燥温度 Drying Temperature			℃	120
干燥时间 Drying Time			hrs	4
料筒温度 Cylinder Temperature			℃	280 ~ 320
模具温度 Mold Temperature			℃	80 ~ 120

* 以上数值是根据实验标准测定的代表数值。因为本资料是根据本公司实验数据所作成，所以这些数据未必适用各种不同的条件，最终还请客户自行作出判断。上述所列的仅是产品的基本信息而不是产品规格。

*如果干燥不充分造成产品偏脆，制品表面有水花，物性下降；如果想获得较光亮的表面请务必保持较高的模温。

* The values above are representative figures determined according to standard test methods. As this information is based on the company's experimental data, these figures may not necessarily apply to all conditions; customers are advised to make their own final assessments. The information listed above represents basic product details rather than formal product specifications.

* Insufficient drying may result in brittleness, surface blemishes (such as water marks), and a decline in physical properties. To achieve a glossier surface finish, please ensure the mold temperature is maintained at a high level.